

# LH538000-S

**CMOS 8M (1M × 8/512K × 16)  
3 V-Drive Mask-Programmable ROM**

## FEATURES

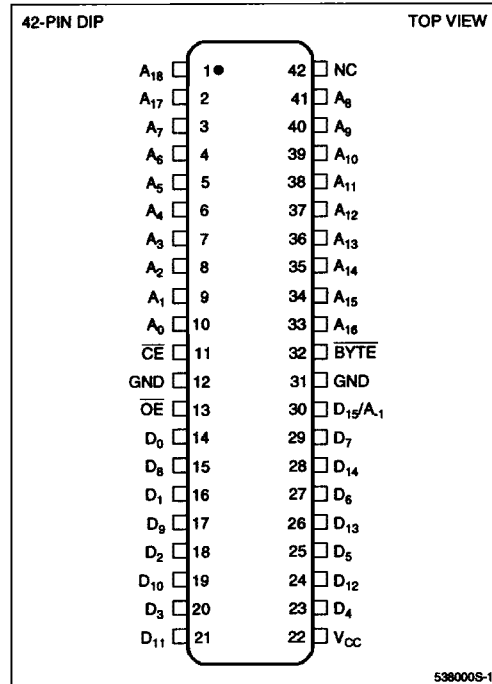
- Low power supply:  
2.6 to 5.5 V
- 1,048,576 × 8 bit organization  
(Byte mode)  
524,288 × 16 bit organization  
(Word mode)
- Access time:  
500 ns (MAX.) at 2.6 V ≤ V<sub>CC</sub> < 4.5 V  
200 ns (MAX.) at 4.5 V ≤ V<sub>CC</sub> ≤ 5.5 V
- Static operation
- Three-state output
- Packages:  
42-pin, 600-mil DIP  
44-pin, 600-mil SOP  
64-pin, 14 × 20 mm<sup>2</sup> QFP  
48-pin, 12 × 18 mm<sup>2</sup> TSOP (Type I)

## DESCRIPTION

The LH538000-S is a CMOS 8M-bit mask-programmable ROM organized as 1,048,576 × 8 bits (Byte mode) or 524,288 × 16 bits (Word mode) that can be selected by BYTE input pin.

It is suited for use in compact battery back-up systems due to be operated on 3 V power supply.

## PIN CONNECTIONS



**Figure 1. Pin Connections for DIP Package**

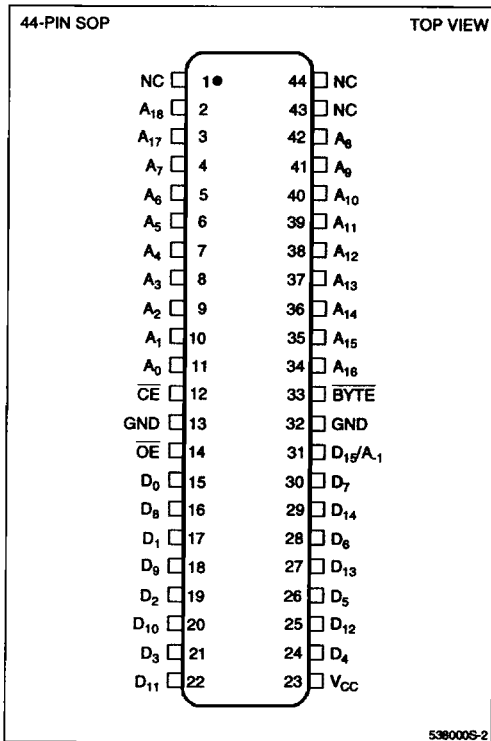


Figure 2. Pin Connections for SOP Package

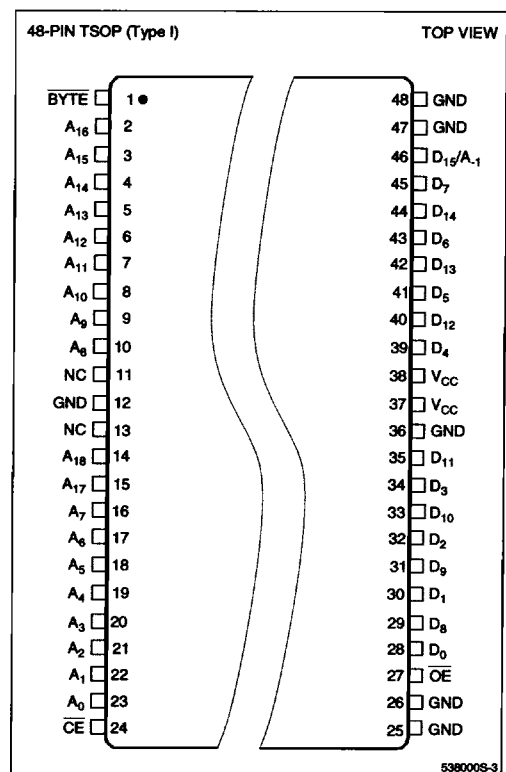


Figure 3. Pin Connections for TSOP Package

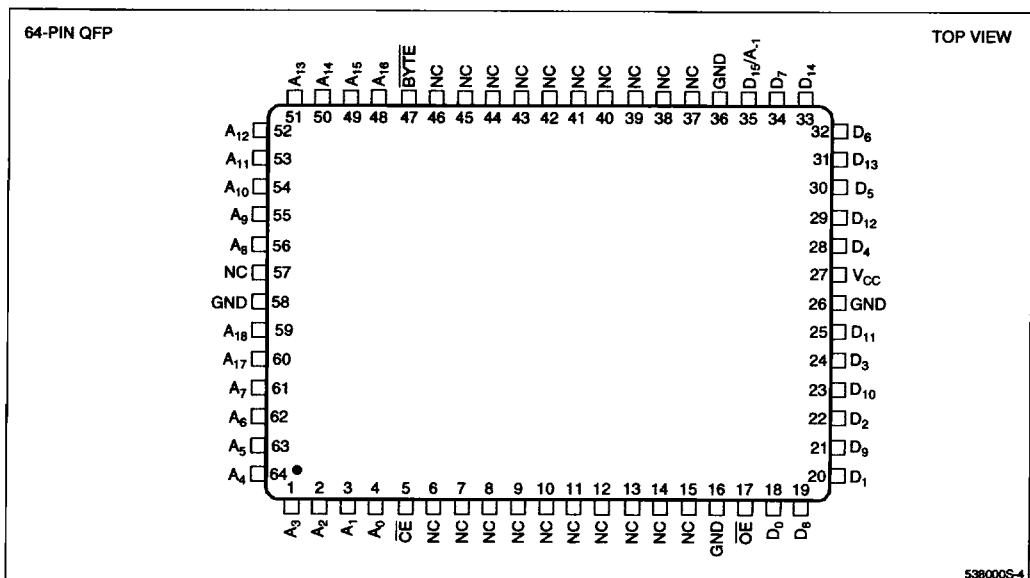


Figure 4. Pin Connections for QFP Package

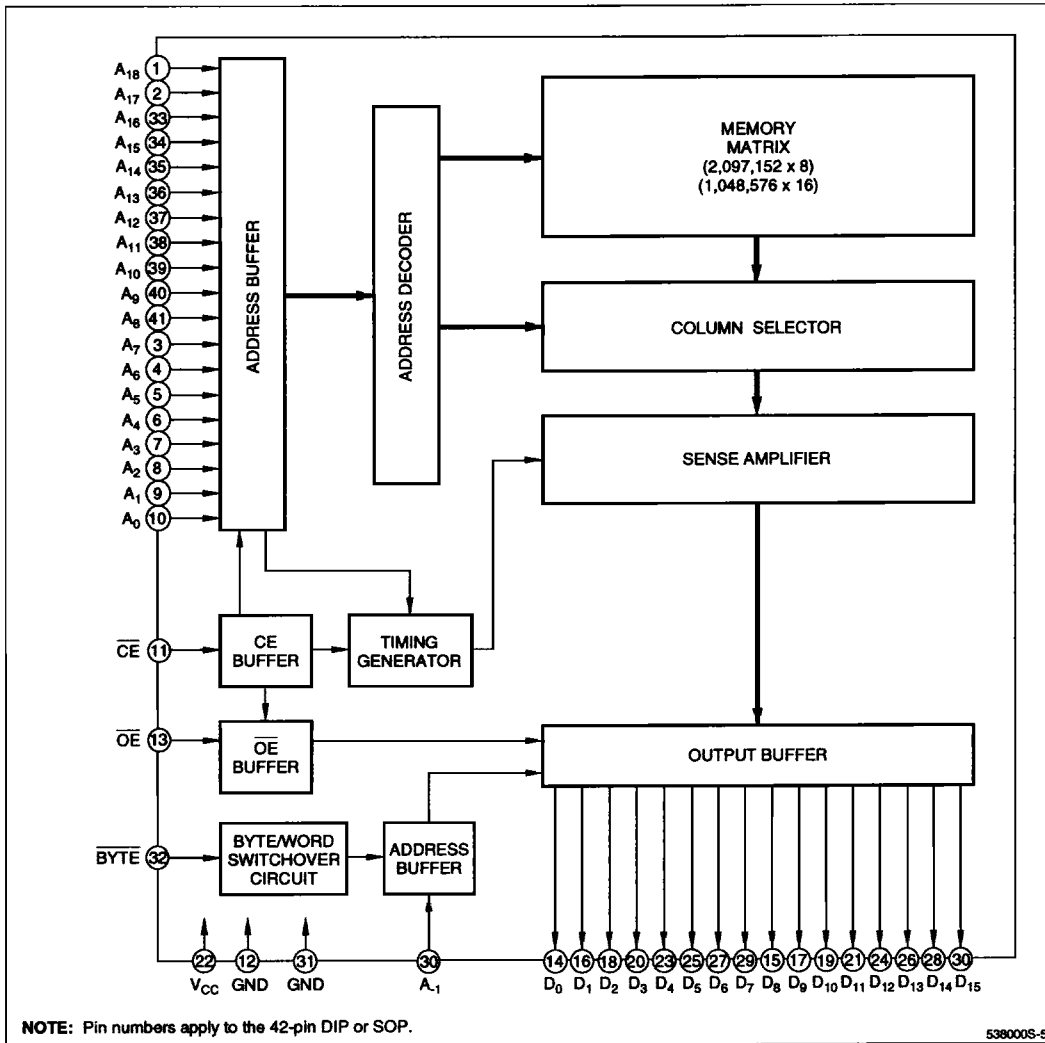


Figure 5. LH538000-S Block Diagram

**PIN DESCRIPTION**

SIGNAL	PIN NAME
A <sub>1</sub> - A <sub>18</sub>	Address input
D <sub>0</sub> - D <sub>15</sub>	Data output
BYTE	Byte/Word switch
$\overline{CE}$	Chip enable input

SIGNAL	PIN NAME
OE	Output enable input
V <sub>cc</sub>	Power supply
GND	Ground

**NOTE:**

The D<sub>15</sub>/A<sub>1</sub> pin becomes LSB address input (A<sub>1</sub>) when the bit configuration is set to byte mode, and data output (D<sub>15</sub>) when in word mode. The BYTE input pin selects bit configuration.

## TRUTH TABLE

$\overline{CE}$	$\overline{OE}$	BYTE	A <sub>1</sub> (D <sub>15</sub> )	DATA OUTPUT		MODE	ADDRESS INPUT		SUPPLY CURRENT
				D <sub>0</sub> - D <sub>7</sub>	D <sub>8</sub> - D <sub>15</sub>		LSB	MSB	
H	X	X	X	High-Z	High-Z	High-Z	-	-	Standby (I <sub>SB</sub> )
L	H	X	X	High-Z	High-Z		-	-	Operating (I <sub>CC</sub> )
L	L	H	Inhibit	D <sub>0</sub> - D <sub>7</sub>	D <sub>8</sub> - D <sub>15</sub>	16-bit	A <sub>0</sub>	A <sub>18</sub>	Operating (I <sub>CC</sub> )
L	L	L	L	D <sub>0</sub> - D <sub>7</sub>	High-Z	8-bit	A <sub>1</sub>	A <sub>18</sub>	Operating (I <sub>CC</sub> )
L	L	L	H	D <sub>8</sub> - D <sub>15</sub>	High-Z	8-bit	A <sub>1</sub>	A <sub>18</sub>	Operating (I <sub>CC</sub> )

## NOTE:

X = Don't care, High-Z = High-impedance

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Supply voltage	V <sub>CC</sub>	-0.3 to +7.0	V
Input voltage	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> + 0.3	V
Output voltage	V <sub>OUT</sub>	-0.3 to V <sub>CC</sub> + 0.3	V
Operating temperature	T <sub>opr</sub>	0 to +70	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 0 to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V <sub>CC</sub>	2.6		5.5	V

DC CHARACTERISTICS (V<sub>CC</sub> = 2.6 to 5.5 V, T<sub>A</sub> = 0 to +70°C)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	MAX.	UNIT	NOTE
Input 'High' voltage	V <sub>IH</sub>		0.8V <sub>CC</sub>	V <sub>CC</sub> + 0.3	V	
Input 'Low' voltage	V <sub>IL</sub>		-0.3	0.4	V	
Output 'High' voltage	V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	0.8V <sub>CC</sub>		V	
Output 'Low' voltage	V <sub>OL</sub>	I <sub>OL</sub> = 400 μA		0.4	V	
Input leakage current	I <sub>I</sub>	V <sub>IN</sub> = 0 V to V <sub>CC</sub>		10	μA	
Output leakage current	I <sub>O</sub>	V <sub>OUT</sub> = 0 V to V <sub>CC</sub>		10	μA	1
Operating current	I <sub>CC1</sub>	t <sub>RC</sub> = 200 ns		50	mA	2
	I <sub>CC2</sub>	t <sub>RC</sub> = 1 μs		40	mA	2
	I <sub>CC3</sub>	t <sub>RC</sub> = 200 ns		45	mA	3
	I <sub>CC4</sub>	t <sub>RC</sub> = 1 μs		35	mA	3
Standby current	I <sub>SB1</sub>	$\overline{CE} = V_{IH}$		3	mA	
	I <sub>SB2</sub>	$\overline{CE} = V_{CC} - 0.2 V$		100	μA	
Input capacitance	C <sub>IN</sub>	f = 1 MHz, T <sub>A</sub> = +25°C		10	pF	
Output capacitance	C <sub>OUT</sub>			10	pF	

## NOTES:

- $\overline{CE} = V_{IH}$ ,  $\overline{OE} = V_{IH}$ , outputs open
- V<sub>IN</sub> = V<sub>IH</sub>, V<sub>IL</sub>,  $\overline{CE} = V_{IL}$ , outputs open
- V<sub>IN</sub> = (V<sub>CC</sub> - 0.2 V), 0.2 V,  $\overline{CE} = 0.2 V$ , outputs open

**AC CHARACTERISTICS (T<sub>A</sub> = 0 to +70°C)**

PARAMETER	SYMBOL	2.6 ≤ V <sub>CC</sub> < 4.5		4.5 ≤ V <sub>CC</sub> ≤ 5.5		UNIT	NOTE
		MIN.	MAX.	MIN.	MAX.		
Read cycle time	t <sub>RC</sub>	500		200		ns	
Address access time	t <sub>AA</sub>		500		200	ns	
Chip enable time	t <sub>ACE</sub>		500		200	ns	
Output enable time	t <sub>OE</sub>		150		80	ns	
Output hold time	t <sub>OH</sub>	10		5		ns	
CE to output in High-Z	t <sub>CHZ</sub>		150		70	ns	1
OE to output in High-Z	t <sub>OHZ</sub>		150		70	ns	

**NOTE:**

1. This is the time required for the outputs to become high-impedance.

**AC TEST CONDITIONS**

PARAMETER	RATING
Input voltage amplitude	0.4 to 2.6 V
Input rise/fall time	10 ns
Input/output reference level	1.5 V
Output load condition	1 TTL + 100 pF

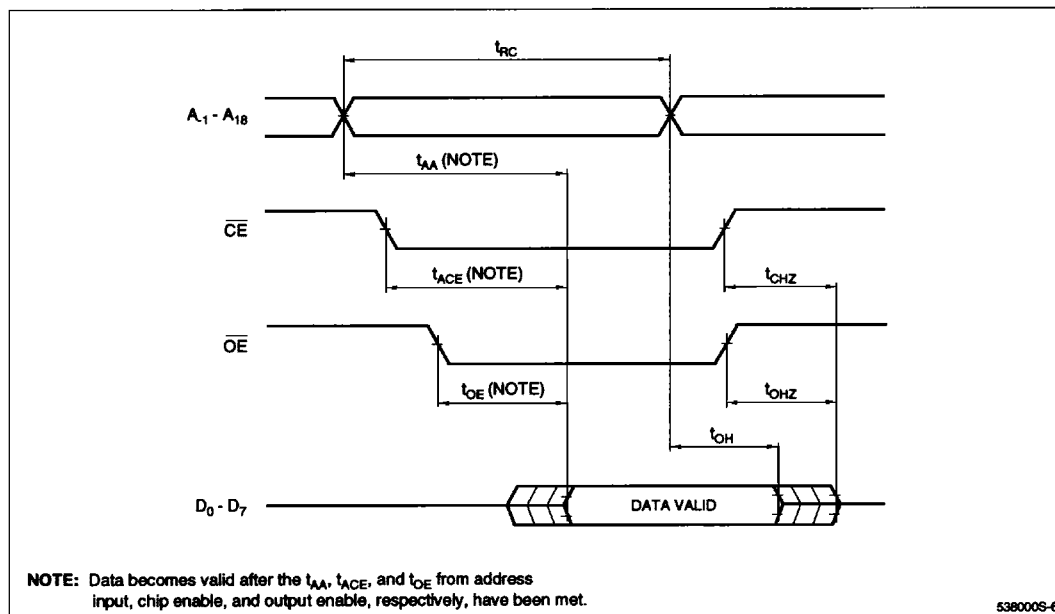


Figure 6. Byte Mode (BYTE = V<sub>IL</sub>)

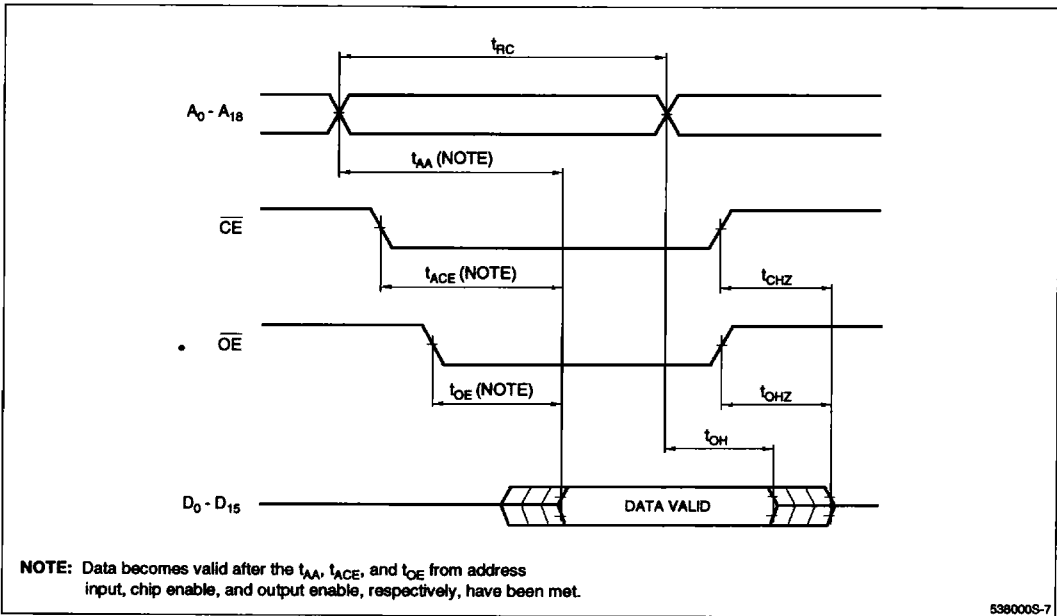


Figure 7. Word Mode ( $\overline{BYTE} = V_{IH}$ )

ORDERING INFORMATION

LH538000-S	X	- ##
Device Type	Package	Speed
		50 500 Access Time (ns)
		<ul style="list-style-type: none"> <li>{ D 42-pin, 600-mil DIP (DIP42-P-600)</li> <li>{ M 64-pin, 14 x 20 mm<sup>2</sup> QFP (QFP64-P-1420)</li> <li>{ N 44-pin, 600-mil SOP (SOP44-P-600)</li> <li>{ T 48-pin, 12 x 18 mm<sup>2</sup> TSOP (TSOP48-P-1218: Type I)</li> </ul>
CMOS 8M (1M x 8 OR 512K x 16) Mask-Programmable ROM		
<b>Example:</b> LH538000-SD-50 (CMOS 8M (1M x 8) Mask-Programmable ROM, 200 ns, 42-pin, 600-mil DIP)		

538000S-8